

**Preliminary Amendment**

Prior to examining the above-captioned case on the merits, please add the following new claims.

a1 -- 24. (new) A method for forming a semiconductor device having a hardwired column address strobe (CAS) latency, comprising:

providing at least one CAS latency select line;

forming at least a first conductive pad electrically coupled with a high potential, a second conductive pad electrically coupled with said CAS latency select line, and a third conductive pad electrically coupled with a low potential; and

selecting a CAS latency by performing one of the following:

forming a conductor to electrically connect said first pad portion with said second pad portion to select a first CAS latency;

forming a conductor to electrically connect said second pad portion with said third pad portion to select a second CAS latency which is different from said first CAS latency.

25. (new) The method of claim 24 further comprising forming a ball bond during said formation of said conductor which electrically connects only two of said first, second, and third conductive pads together.

26. (new) The method of claim 24 further comprising forming a bond wire during said formation of said conductor which electrically connects only two of said first, second, and third conductive pads together.

27. (new) The method of claim 24 further comprising encapsulating said CAS select line and said first, second, and third conductive pads subsequent to forming said conductor. --